



PARA LIGHT ELECTRONICS CO., LTD.

4F, No.1, Lane 93, Chien Yi Road, Chung Ho City, Taipei, Taiwan, R.O.C.

Tel: 886-2-2225-3733

Fax: 886-2-2225-4800

E-mail: para@para.com.tw

<http://www.para.com.tw>

DATA SHEET

PART NO. : L-955EC-TR

REV : A / 0

CUSTOMER'S APPROVAL : _____

DCC : _____

DRAWING NO. : DS-31-03-0121

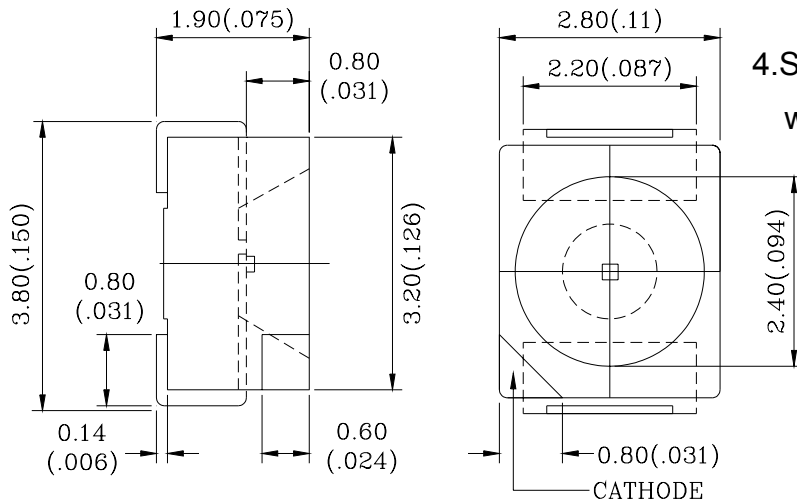
DATE : 2003-07-15

Page : 1

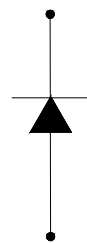
PACKAGE DIMENSIONS

Note:

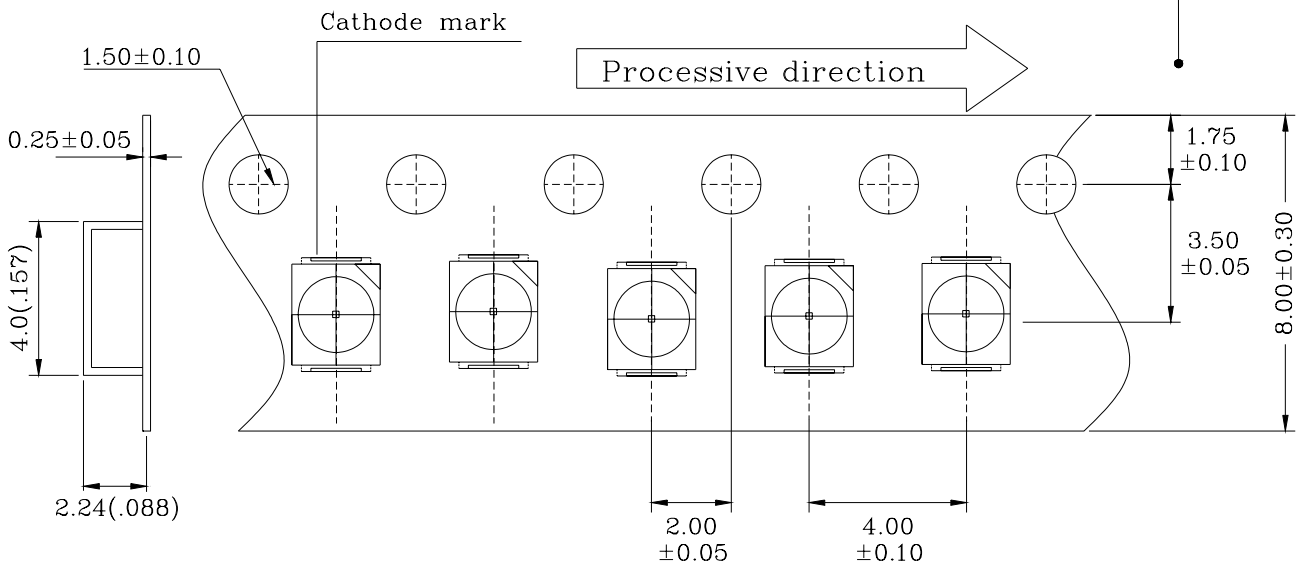
1. All Dimensions are in millimeters.
2. Tolerance is $\pm 0.25\text{mm}$ (0.010 ") Unless otherwise specified.
3. Lead spacing is measured where the leads emerge from the package.
4. Specification are subject to change without notice



Polarity



TAPE SPECIFICATIONS:





3.2*2.8*1.9 mm SMD LED LAMP

L-955EC-TR

REV:A / 0

FEATURES

- * HIGH BRIGHTNESS SURFACE MOUNT LED
- * BASED ON INGAN TECHNOLOGY
- * 120° VIEWING ANGLE
- * SMALL PACKAGE OUTLINE (L*W*H)OF 2.8*3.2*1.9MM)
- * QUALIFIED ACCORDING TO JEDEC MOISTURE SENSITIVITY LEVEL 2
- * COMPATIBLE TO BOTH IR REFLOW SOLDERING AND TTW SOLDERING

CHIP MATERIALS

- * Dice Material : GaAsP
- * Light Color : RED
- * Lens Color : WATER CLEAR

ABSOLUTE MAXIMUM RATING : (Ta = 25°C)

SYMBOL	PARAMETER	RED	UNIT
PAD	Power Dissipation Per Chip	80	mW
VR	Reverse Voltage Per Chip	5	V
IAF	Continuous Forward Current Per Chip	30	mA
IPF	Peak Forward Current Per Chip (Duty – 0.1,1KHz)	120	mA
–	Derating Linear From 25°C Per Chip	0.40	mA/°C
Topr	Operating Temperature Range	-40°C to +100°C	
Tstg	Storage Temperature Range	-40°C to+100°C	

Lead Soldering Temperature { 1.6mm(0.063 inch) From Body } 260°C ± 5°C for 3 Seconds

ELECTRO-OPTICAL CHARACTERISTICS : (Ta = 25°C)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage	IF = 20mA		2.2	2.6	V
IR	Reverse Current	VR = 5V			100	µA
λD	Dominant Wavelength	IF = 20mA		625		nm
Δλ	Spectral Line Half-Width	IF = 20mA		35		nm
2θ1/2	Half Intensity Angle	IF = 20mA		120		deg
IV	Luminous Intensity	IF = 20mA	11.2	18		mcd

